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IN THE SPECIFICATION:

Please amend the specification with the replacement paragraphs as follows:

[0011] Figure 1 illustrates a foreign matter particle 13 trapped between an electrostatic chuck 12 and the conductive backside coating 11 of a device 10 (e.g., EUVL Reticle). As shown in Figure 1, the foreign matter ~~particles~~ particle 13 causes the front side of the device 10 to undesirably deform from its completely flat position.

[0012] Electrostatic pin chucks are an alteration of the above electrostatic chuck 12. The electrostatic pin chuck 20 shown in Figure 2 includes numerous small electrostatic pins 21 that are in the same plane to hold the device 10. This structure 20 has an advantage over the standard electrostatic chuck 12 in that the surface area of the chuck is decreased, which consequently decreases the probability of a particle being caught between the backside of the device 10 and the electrostatic pin ~~chuck~~ 21 surfaces. However, this format does not eliminate the problem completely and ~~particles~~ particle 13 still can become stuck between the electrostatic pin chuck ~~21~~ 20 and the backside of the device 10, causing deformation of the otherwise flat device 10, as shown in Figure 2.

[0014] The structure shown in Figure 3 avoids such problems by making the pin height of the electrostatic pin chuck adjustable. More specifically, the adaptive electrostatic pin chuck 30 ~~31~~ shown in Figure 3 includes height adjustment mechanisms 32 between the base plate 31 of the chuck 30 and the electrostatic pin ~~chuck~~ 21. Hence, if a particle 13 is

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lodged between the electrostatic pin chuck 21 and the backside of the device 10, the

electrostatic pin chuck 21 height is adjusted to compensate for the particle 13 and the

flatness of the device 10 is not compromised, as shown in Figure 3. The base plate 31

should have significant structural integrity such that the shape of device being clamped is

changed, not the shape of the base plate.

[0015] The structure shown in Figure 3 provides a significant advantage because the

height of the individual electrostatic pins 21 are automatically adjusted. This

compensates for any base plate 31 warpage or particles particle 13 that could interfere

with the flatness of the device 10 at processing steps where flatness is crucial, such as

write, inspection, exposure, etc.

[0017] Figure 4 illustrates a system embodiment of the invention. This system provides a

measurement tool (interferometer) 40 adapted to measure the flatness of the device (e.g.,

mask) held by the electrostatic chuck pins 21, and a computer 41 connected to the

measurement tool toll and height adjustment mechanisms 32. A computer algorithm

takes the measurement tool 40 41 output and compares it to a preset flatness

specification. The computer algorithm then adjusts each individual pin height through

the interface between the computer and the individual electrostatic chuck pins 21. This

process is repeated until the flatness of the device is within a preset tolerance. Any

computer program based on some type of process control would be adequate, although

the performance of the individual process control sequence may vary. The computer is

adapted to change the shape of the device to conform to a pre-existing standard.

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